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Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

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Ji Yong Park is currently a VP (Vice President) at SK hynix, where he leads the PKG Innovation team focusing on VFO (Vertical Fan Out) and SiP (System in Package) technologies. Prior to joining SK hynix in 2025, he worked at Intel in Chandler, Arizona, from 2013 to 2024, as a senior staff engineer and ATTD technologist in the packaging technology field. His contributions at Intel included the development of TCB (Thermal Compression Bonding) tools and processes, pathfinding for EMIB substrates, and leading memory integration efforts for HBM and LP5x DRAM (played a key role in the successful launch of Intel Xeon CPU Max and Data Center GPU Max).

He received his B.S. and M.S. in Materials Science and Engineering from POSTECH, and his Ph.D. in Materials Science and Engineering from the University of Illinois at Urbana-Champaign.